

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Jin-Ho PARK</td><td>01/12/2011</td></tr> <tr><td>Jin Ho PARK</td><td>01/12/2011</td></tr> <tr><td>Jae-Young LIM</td><td>01/12/2011</td></tr> <tr><td>Sang-Heon KWAK</td><td>01/12/2011</td></tr> <tr><td>Sung-Chul KIM</td><td>01/12/2011</td></tr> <tr><td>Kyung-Sik CHOI</td><td>01/12/2011</td></tr> <tr><td>Hyeong-Jae CHOI</td><td>01/12/2011</td></tr> </tbody> </table>		Name	Execution Date	Jin-Ho PARK	01/12/2011	Jin Ho PARK	01/12/2011	Jae-Young LIM	01/12/2011	Sang-Heon KWAK	01/12/2011	Sung-Chul KIM	01/12/2011	Kyung-Sik CHOI	01/12/2011	Hyeong-Jae CHOI	01/12/2011
Name	Execution Date																
Jin-Ho PARK	01/12/2011																
Jin Ho PARK	01/12/2011																
Jae-Young LIM	01/12/2011																
Sang-Heon KWAK	01/12/2011																
Sung-Chul KIM	01/12/2011																
Kyung-Sik CHOI	01/12/2011																
Hyeong-Jae CHOI	01/12/2011																
RECEIVING PARTY DATA																	
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td>Name:</td><td>Pantech Co., Ltd.</td></tr> <tr><td>Street Address:</td><td>Pantech R&D Center, I-2, DMC</td></tr> <tr><td>Internal Address:</td><td>Sangam-dong, Mapo-gu</td></tr> <tr><td>City:</td><td>Seoul</td></tr> <tr><td>State/Country:</td><td>REPUBLIC OF KOREA</td></tr> <tr><td>Postal Code:</td><td>121-270</td></tr> </table>		Name:	Pantech Co., Ltd.	Street Address:	Pantech R&D Center, I-2, DMC	Internal Address:	Sangam-dong, Mapo-gu	City:	Seoul	State/Country:	REPUBLIC OF KOREA	Postal Code:	121-270				
Name:	Pantech Co., Ltd.																
Street Address:	Pantech R&D Center, I-2, DMC																
Internal Address:	Sangam-dong, Mapo-gu																
City:	Seoul																
State/Country:	REPUBLIC OF KOREA																
Postal Code:	121-270																
PROPERTY NUMBERS Total: 1																	
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13006026</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13006026												
Property Type	Number																
Application Number:	13006026																
CORRESPONDENCE DATA																	
<p>Fax Number: (703)288-5139 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-288-5105 Email: patent@park-law.com Correspondent Name: H.C. Park & Associates, PLC Address Line 1: 8500 Leesburg Pike Address Line 2: Suite 7500 Address Line 4: Vienna, VIRGINIA 22182</p>																	

OP \$40.00 13006026

501480896

PATENT
REEL: 026027 FRAME: 0076

ATTORNEY DOCKET NUMBER:	P4150US00
NAME OF SUBMITTER:	Hae-Chan Park
<p>Total Attachments: 4</p> <p>source=P4150US00_Assignment#page1.tif</p> <p>source=P4150US00_Assignment#page2.tif</p> <p>source=P4150US00_Assignment#page3.tif</p> <p>source=P4150US00_Assignment#page4.tif</p>	



ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

☒ an application for United States Letters Patent entitled **METHOD FOR AUTHORIZING USE OF AUGMENTED REALITY (AR) INFORMATION AND APPARATUS** ("Application");

☐ upon which United States Letters Patent, Patent Number _____, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

PANTECH CO., LTD.
Pantech R&D Center, I-2, DMC
Sangam-dong, Mapo-gu
Seoul 121-270
Republic of Korea

PANTECH CO., LTD. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary



or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Jin-Ho PARK

Address: 266-15 Seokgwan-dong
Seongbuk-gu
Seoul
Republic of Korea

First Inventor's Signature: 

Date: 1-12-2011

Second Inventor's Name: Jin-Ho PARK

Address: 1001-703 Jugong 10danji Apt.
Haan 4-dong, Gwangmyeong-si
Gyeonggi-do
Republic of Korea

Second Inventor's Signature: 

Date: 1-12-2011

Third Inventor's Name: Jae-Young LIM

Address: 202-602 Sinmyeong Boram Apt.
497-1 Bugae 3-dong, Bupyeong-gu
Incheon-si
Republic of Korea

Third Inventors' Signature: 

Date: 1-12-2011



Fourth Inventor's Name:

Sang-Heon KWAK

Address:

601-304 Bangasi Maeul, Jeongbalsan-dong
Ilsandong-gu, Goyang-si
Gyeonggi-do
Republic of Korea

Fourth Inventor's Signature:

Date:

1-12-2011

Fifth Inventor's Name

Sung-Chul KIM

Address:

201ho, Gyeongdeok Apt.,
72-9 Samjeon-dong, Songpa-gu
Seoul
Republic of Korea

Fifth Inventor's Signature:

Date:

1-12-2011

Sixth Inventor's Name:

Kyung-Sik CHOI

Address:

103-1101 Hanwha Kkumegreen Apt.
Bisan 2-dong, Dongan-gu, Anyang-si
Gyeonggi-do
Republic of Korea

Sixth Inventor's Signature:

Date:

1-12-2011



Seventh Inventor's Name:

Hyeong-Jae CHOI

Address:

802-506 Soman 8danji Apt.
Haengsin-dong, Deogyang-gu, Goyang-si
Gyeonggi-do
Republic of Korea

Seventh Inventor's Signature:

Date:

1 - 12 - 2011